

column-shaped section, an axis of said column-shaped section being parallel to a direction of extension of said lead terminals; and

94 a resin fixture intervening between said electrically conductive casing and said semiconductor element module, said resin fixture mounted with said semiconductor element module and fitted to said electrically conductive casing, said resin fixture having a cylinder-shaped section for retaining, in its inner periphery, said column-shaped section of said semiconductor element module, an outer periphery surface of said cylinder-shaped section being plated and an inner periphery surface of said cylinder-shaped section not being plated.

17. (Amended) An electronic apparatus according to claim 20, wherein said semiconductor element module has a raised portion formed on its outer surface at a site where said semiconductor element module is fitted to said resin fixture, and wherein

95 said resin fixture has a recessed portion formed in the inner surface at a site where said semiconductor module is mounted, said recessed portion being fitted to said raised portion.

18. (Amended) An electronic apparatus according to claim 20, wherein said semiconductor element module has an externally threaded portion formed on its outer surface at a site where said semiconductor element module is fitted to said resin fixture, and wherein

said resin fixture has an internally threaded portion formed in the inner surface at a site where said semiconductor module is mounted, said externally threaded portion being screwed into said internally threaded portion.

93 19. (Amended) An electronic apparatus according to claim 20, wherein said semiconductor element module has a recessed portion formed in its outer surface at a site where said semiconductor element module is fitted to said resin fixture, and wherein

said resin fixture has a raised portion formed on its inner surface at a site where said semiconductor module is mounted, said raised portion being fitted to said recessed portion.

94 20. (New) An electronic apparatus comprising:  
an electronic circuit board;  
an electrically conductive casing for encasing said electronic circuit board;  
an optical semiconductor element module electrically connected to said electronic circuit board; and  
a resin fixture intervening between said electrically conductive casing and said optical semiconductor element module, said resin fixture mounted with said optical semiconductor element module and fitted to said electrically conductive casing, said resin fixture having a base opposing a surface of said electrically conductive casing onto which an opening is provided for the electrical connection of said optical semiconductor element

module and two arms extending from said base along side surfaces of said electrically conductive casing and forming approximate U-shape along with said base, wherein

a plurality of notched portions are formed on an external surface of said base of said resin fixture;

96 a plurality of hooked portions are formed on said side surfaces of said electrically conductive casing in positions which fit said notched portions;

a protrusion is formed on the external surface and near a tip of each of said arms of said resin fixture; and

an aperture is formed on each of said side surfaces of said conductive casing at a position corresponding to said protrusion.